



256Kx32 Static RAM CMOS, High Speed Module

FEATURES

- 256Kx32 bit CMOS Static RAM
 - Access Times: 12, 15, 20, and 25ns
 - Individual Byte Selects
 - Fully Static, No Clocks
 - TTL Compatible I/O
- High Density Package with JEDEC Standard Pinouts
 - 72 Pin SIMM No. 175 (Angle)
 - 72 Pin ZIP No. 176
 - 72 Pin SIMM, No. 354 (Straight)
- Single +3.3V ($\pm 10\%$) Supply Operation

DESCRIPTION

The EDI8F32259V is a high speed 8Mb Static RAM module organized as 256K words by 32 bits. This module is constructed from eight 256Kx4 Static RAMs in SOJ packages on an epoxy laminate (FR4) board.

Four chip enables ($\overline{E0}$ - $\overline{E3}$) are used to independently enable the four bytes. Reading or writing can be executed on individual bytes or any combination of multiple bytes through proper use of selects.

The EDI8F32259V is offered in 72 pin ZIP/SIMM package which enables eight megabits of memory to be placed in less than 1.3 square inches of board space.

All inputs and outputs are TTL compatible and operate from a single 3.3V supply. Fully asynchronous circuitry requires no clocks or refreshing for operation and provides equal access and cycle times for ease of use.

The ZIP and SIMM modules contain four PD (Presence Detect) pins which are used to identify module memory density in applications where alternate modules can be interchanged.

FIG. 1

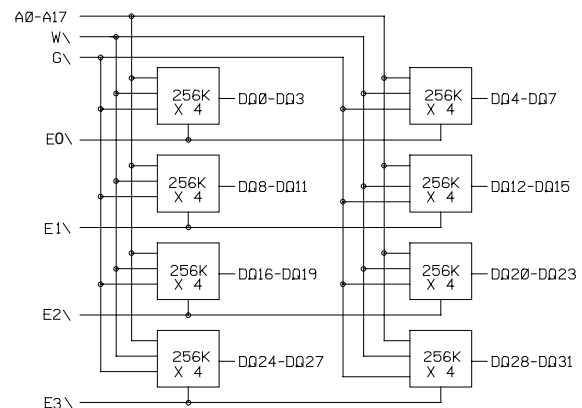
PIN CONFIGURATIONS AND BLOCK DIAGRAM

NC	1	E4\	37
NC	2	E3\	38
PD3	3	A17	39
PD4	4	A16	40
VSS	5	G\	41
PD1	6	VSS	42
PD2	7	DQ24	43
DQ0	8	DQ16	44
DQ8	9	DQ25	45
DQ1	10	DQ17	46
DQ9	11	DQ26	47
DQ2	12	DQ18	48
DQ10	13	DQ27	49
DQ3	14	DQ19	50
DQ11	15	A3	51
VCC	16	A10	52
A0	17	A4	53
A7	18	A11	54
A1	19	A5	55
A8	20	A12	56
A2	21	VCC	57
A9	22	A13	58
DQ12	23	A6	59
DQ4	24	DQ20	60
DQ13	25	DQ28	61
DQ5	26	DQ21	62
DQ14	27	DQ29	63
DQ6	28	DQ22	64
DQ15	29	DQ30	65
DQ7	30	DQ23	66
VSS	31	DQ31	67
W\	32	VSS	68
A15	33	NC	69
A14	34	NC	70
E2\	35	NC	71
E1\	36	NC	72

PD 1,2 = VSS
PD 3,4 = Open

PIN NAMES

A0-A17	Address Inputs
$\overline{E0}$ - $\overline{E3}$	Chip Enables
$\overline{W}$, $\overline{G}$	Write Enables
$\overline{G}$	Output Enable
DQ0-DQ31	Common Data Input/Output
VCC	Power (3.3V $\pm 10\%$)
VSS	Ground





ABSOLUTE MAXIMUM RATINGS*

Voltage on any pin relative to VSS	-0.5V to 4.6V
Operating Temperature TA (Ambient)	0°C to +70°C
Commercial	0°C to +70°C
Storage Temperature, Plastic	-55°C to +125°C
Power Dissipation	2.5 Watts
Output Current	20 mA

*Stress greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions greater than those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

Parameter	Sym	Min	Typ	Max	Units
Supply Voltage	VCC	3.0	3.3	3.6	V
Supply Voltage	VSS	0	0	0	V
Input High Voltage	VIH	2.2	--	VCC+0.3V	V
Input Low Voltage	VIL	-0.3	--	0.8	V

AC TEST CONDITIONS

Input Pulse Levels	VSS to 3.0V
Input Rise and Fall Times	5ns
Input and Output Timing Levels	1.5V
Output Load	1TTL, CL = 30pF

(note: For TEHQZ, TGHQZ and TWLQZ, CL = 5pF)

DC ELECTRICAL CHARACTERISTICS

Parameter	Sym	Conditions	Min	Max	Units
				12-25	ns
Operating Power Supply Current	ICC1	$\overline{W}, \overline{E} = VIL, I/O = 0mA, \text{Min Cycle}$		800	mA
Standby (TTL) Power Supply Current	ICC2	$\overline{E} \geq VIH, VIN \leq VIL \text{ or } VIN \geq VIH$		240	mA
Full Standby Power Supply Current	ICC3	$\overline{E} \geq VCC-0.2V$		40	mA
CMOS		$VIN \geq VCC-0.2V \text{ or } VIN \leq 0.2V$			
Input Leakage Current	ILI	$VIN = 0V \text{ to } VCC$	--	±80	µA
Output Leakage Current	ILO	$V I/O = 0V \text{ to } VCC$	--	±20	µA
Output High Voltage	VOH	$IOH = -4.0mA$	2.4	--	V
Output Low Voltage	VOL	$IOL = 8.0mA$	--	0.4	V

TRUTH TABLE

$\overline{E}$	$\overline{W}$	$\overline{G}$	Mode	Output	Power
H	X	X	Standby	HIGH Z	ICC3
L	H	L	Read	DOUT	ICC1
L	L	X	Write	DIN	ICC1
L	H	H	Output Deselect	HIGH Z	ICC1

CAPACITANCE

(f=1.0MHz, VIN=VCC or VSS)

Parameter	Sym	Max	Unit
Address Lines	CI	60	pF
Data Lines	CD/Q	20	pF
Chip Enable Line	CC	20	pF
Write Control Line	CN	60	pF

These parameters are sampled, not 100% tested.



AC CHARACTERISTICS READ CYCLE

Parameter	Symbol		12ns		15ns		20ns		25ns		Units
	JEDEC	Alt.	Min	Max	Min	Max	Min	Max	Min	Max	
Read Cycle Time	TAVAV	TRC	12		15		20		25		ns
Address Access Time	TAVQV	TAA	12		15		20		25		ns
Chip Enable Access	TELQV	TACS	12		15		20		25		ns
Chip Enable to Output in Low Z (1)	TELQX	TCLZ	3		3		3		3		ns
Chip Disable to Output in High Z (1)	TEHQZ	TCHZ	6		7		9		9		ns
Output Hold from Address Change	TAVQX	TOH	3		3		3		3		ns
Output Enable to Output Valid	TGLQV	TOE	6		7		9		9		ns
Output Enable to Output in Low Z (1)	TGLQX	TOLZ	0		0		0		0		ns
Output Disable to Output in High Z (1)	TGHQZ	TOHZ	6		7		9		9		ns

Note 1: Parameter guaranteed, but not tested.

FIG. 2

READ CYCLE 1 - $\overline{W}$ HIGH, $\overline{G}$, $\overline{E}$ LOW

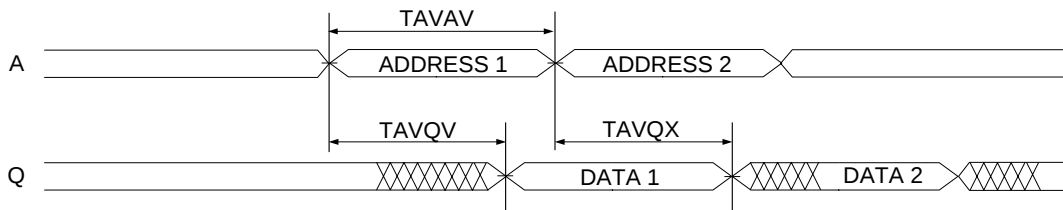
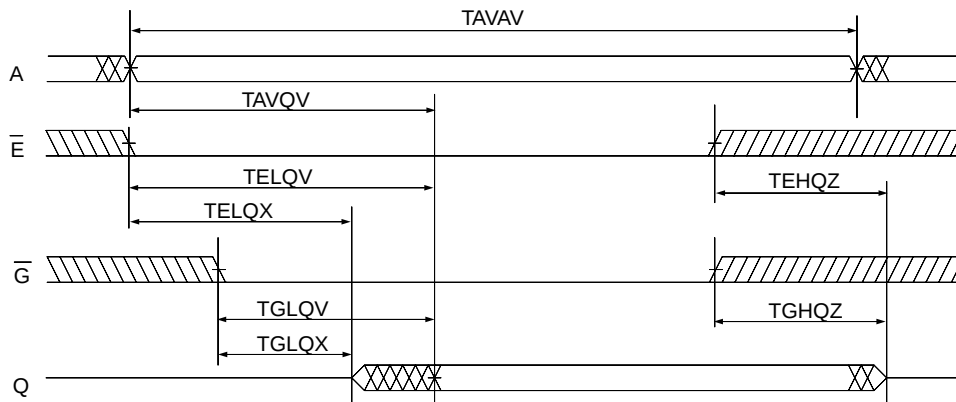


FIG. 3

READ CYCLE 2 - $\overline{W}$ HIGH



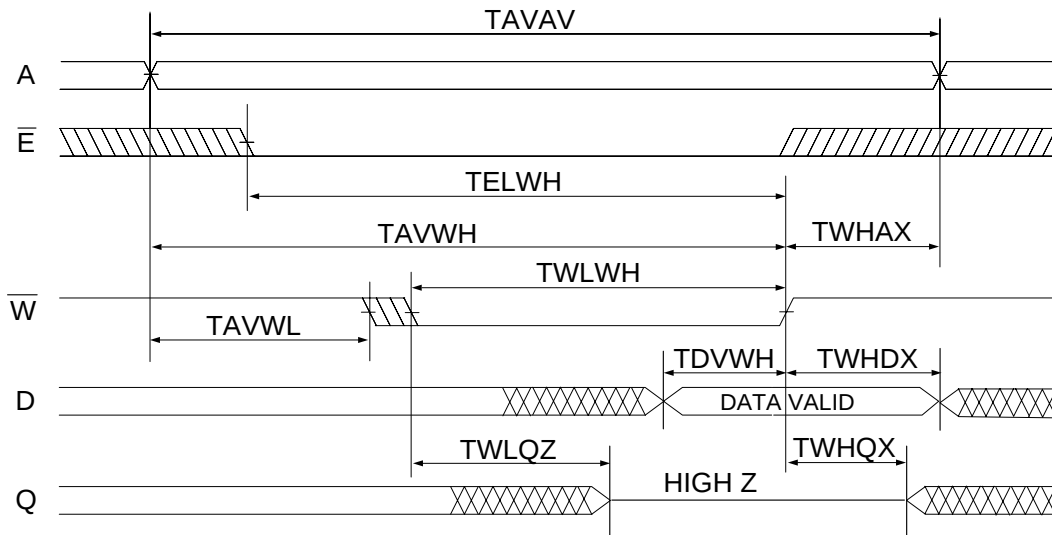

AC CHARACTERISTICS WRITE CYCLE

Parameter	Symbol		12ns		15ns		20ns		25ns		Units
	JEDEC	Alt.	Min	Max	Min	Max	Min	Max	Min	Max	
Write Cycle Time	TAVAV	TWC	12		15		20		25		ns
Chip Enable to End of Write	TELWH	TCW	8		9		10		10		ns
	TWLEH	TCW	8		9		10		10		ns
Address Setup Time	TAVWL	TAS	0		0		0		0		ns
	TAVEL	TAS	0		0		0		0		ns
Address Valid to End of Write	TAVWH	TAW	8		9		10		10		ns
	TAVEH	TAW	8		9		10		10		ns
Write Pulse Width	TWLWH	TWP	8		9		10		10		ns
	TELEH	TWP	8		9		10		10		ns
Write Recovery Time	TWHAX	TWR	0		0		0		0		ns
	TEHAX	TWR	0		0		0		0		ns
Data Hold Time	TWHDX	TDH	3		3		3		3		ns
	TEHDX	TDH	3		3		3		3		ns
Write to Output in High Z (1)	TWLQZ	TWHZ	0	6	0	7	0	9	0	9	ns
Data to Write Time	TDVWH	TDW	6		7		8		8		ns
	TDVEH	TDW	6		7		8		8		ns
Output Active from End of Write (1)	TWHQX	TWLZ	3		3		3		3		ns

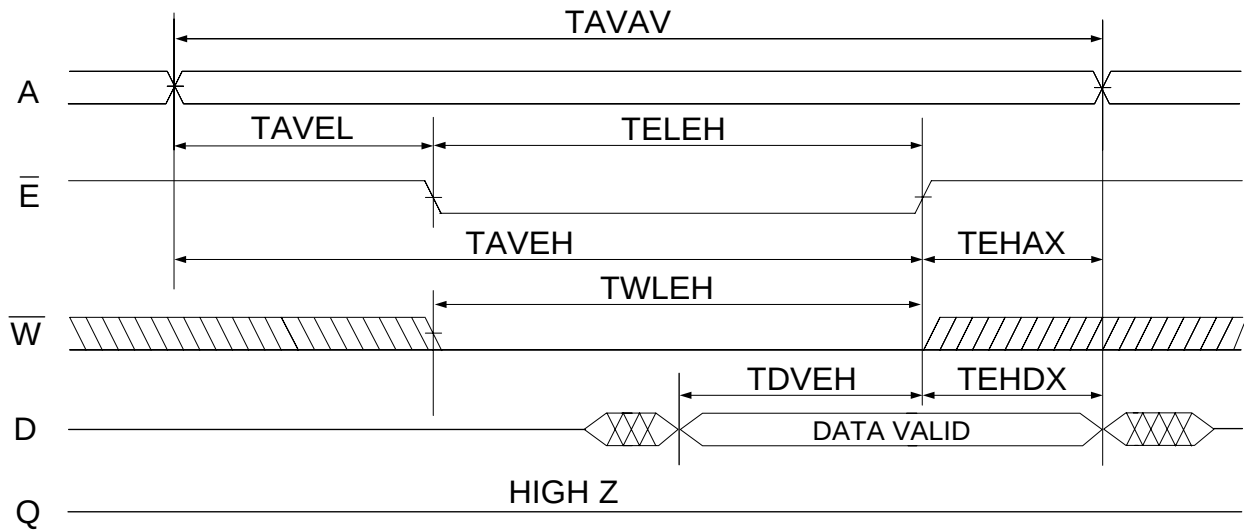
Note 1: Parameter guaranteed, but not tested.



WRITE CYCLE 1 - $\overline{W}$ CONTROLLED



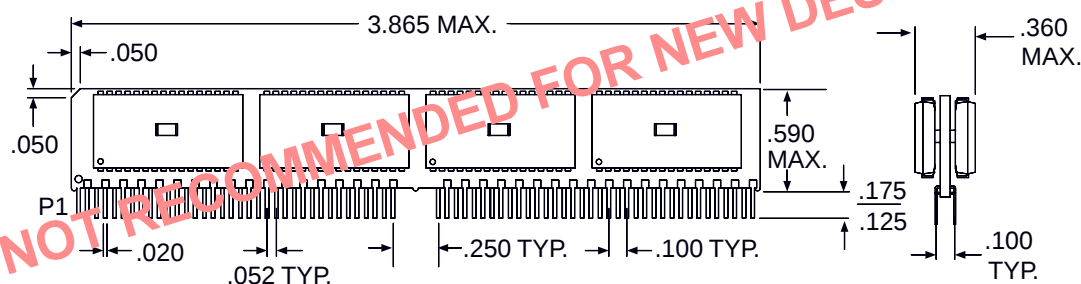
WRITE CYCLE 2 - $\overline{E}$ CONTROLLED



**ORDERING INFORMATION**

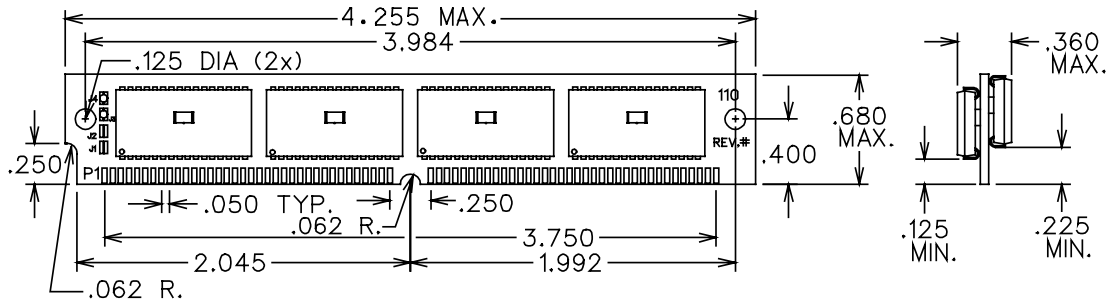
Part Number	Speed (ns)	Package No.
EDI8F32259V12MNC	12	176
EDI8F32259V15MNC	15	176
EDI8F32259V20MNC	20	176
EDI8F32259V25MNC	25	176
EDI8F32259V12MMC	12	354
EDI8F32259V15MMC	15	354
EDI8F32259V20MMC	20	354
EDI8F32259V25MMC	25	354
EDI8F32259V12MZC	12	175
EDI8F32259V15MZC	15	175
EDI8F32259V20MZC	20	175
EDI8F32259V25MZC	25	175

Note: For Gold SIMM, Change from EDI8F to EDI8G.

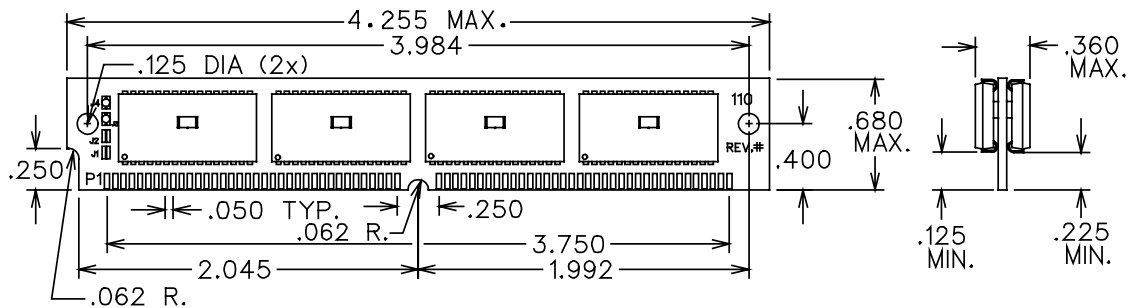
PACKAGE DESCRIPTION**PACKAGE NO. 175: 72 PIN ZIP**



PACKAGE NO. 176: 72 PIN SIMM ANGLED



PACKAGE NO. 354: 72 PIN SIMM STRAIGHT



ALL DIMENSIONS ARE IN INCHES